

## 50-mA, 24-V, 3.2- $\mu$ A SUPPLY CURRENT, LOW-DROPOUT LINEAR REGULATOR

### FEATURES

- **Controlled Baseline**
  - One Assembly Site
  - One Test Site
  - One Fabrication Site
- **Extended Temperature Performance of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product-Change Notification**
- **Qualification Pedigree<sup>(1)</sup>**
- **24-V Maximum Input Voltage**
- **Low 3.2- $\mu$ A Quiescent Current at 50 mA**
- **Stable With Any Capacitor ( $\geq 0.47 \mu\text{F}$ )**
- **50-mA Low-Dropout Regulator**
- **Adjustable Output Voltage (1.2 V to 15 V)**
- **Designed to Support MSP430 Families:**
  - **1.9-V Version Ensured to be Higher Than Minimum  $V_{\text{IN}}$  of 1.8 V**
  - **2.3-V Version Ensured to Meet 2.2-V Minimum  $V_{\text{IN}}$  for Flash on MSP430F2xx**
  - **3.45-V Version Ensured to be Lower Than Maximum  $V_{\text{IN}}$  of 3.6 V**
  - **Wide Variety of Fixed Output Voltage Options to Match  $V_{\text{IN}}$  to the Minimum Required for Desired MSP430 Speed**

<sup>(1)</sup> Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- **Minimum/Maximum Specified Current Limit**
- **5-Pin SC70/SOT-323 (DCK) Package**
- **For 80-mA Rated Current and Higher Power Package, See [TPS715Axx](#)**

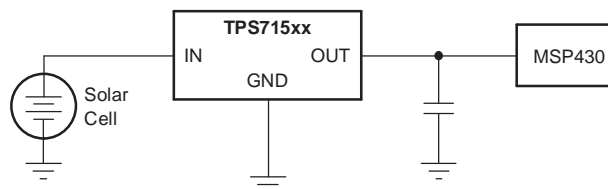
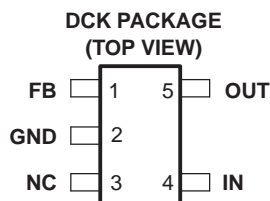
### APPLICATIONS

- **Ultra-Low Power Microcontrollers**
- **Cellular/Cordless Handsets**
- **Portable/Battery-Powered Equipment**

### DESCRIPTION

The TPS71501 low-dropout (LDO) voltage regulators offer the benefits of high input voltage, low dropout voltage, low-power operation, and miniaturized packaging. The device, which operates over an input range of 2.5 V to 24 V, is stable with any capacitor ( $\geq 0.47 \mu\text{F}$ ). The low dropout voltage and low quiescent current allow operation at extremely low power levels. Therefore, the devices are ideal for powering battery-management ICs. Specifically, because the devices are enabled as soon as the applied voltage reaches the minimum input voltage, the output is quickly available to power continuously operating battery-charging ICs.

The usual PNP pass transistor has been replaced by a PMOS pass element. Because the PMOS pass element behaves as a low-value resistor, the low dropout voltage, typically 415 mV at 50 mA of load current, is directly proportional to the load current. The low quiescent current (3.2  $\mu\text{A}$  typically) is stable over the entire range of output load current (0 mA to 50 mA).



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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

**ORDERING INFORMATION<sup>(1)</sup>**

T <sub>J</sub>	PACKAGE <sup>(2)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-55°C to 125°C	SC70 – DCK	Reel of 3000	TPS71501MDCKREP	CVP

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at [www.ti.com](http://www.ti.com).
- (2) Package drawings, thermal data, and symbolization are available at [www.ti.com/packaging](http://www.ti.com/packaging).

**ABSOLUTE MAXIMUM RATINGS**

over operating junction temperature range unless otherwise noted<sup>(1)(2)</sup>

V <sub>IN</sub>	Input voltage range	IN	-0.3 V to 24 V
V <sub>OUT</sub>	Output voltage range	OUT	-0.3 V to 6 V
	Peak output current		Internally limited
	Continuous total power dissipation		See Dissipation Ratings Table
T <sub>J</sub>	Junction temperature range		-55°C to 150°C
T <sub>stg</sub>	Storage temperature range		-65°C to 150°C
ESD	Electrostatic discharge rating	Human-Body Model (HBM)	2000 V
		Charged-Device Model (CDM)	500 V

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under the Electrical Characteristics is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to the network ground terminal.

**DISSIPATION RATINGS**

BOARD	PACKAGE	R <sub>θJC</sub> °C/W	R <sub>θJA</sub> °C/W	DERATING FACTOR ABOVE T <sub>A</sub> = +25°C	T <sub>A</sub> ≤ 25°C POWER RATING	T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 85°C POWER RATING
Low-K <sup>(1)</sup>	DCK	165	395	2.52 mW/°C	250 mW	140 mW	100 mW
High-K <sup>(2)</sup>	DCK	165	315	3.18 mW/°C	320 mW	175 mW	130 mW

- (1) The JEDEC Low-K (1s) board design used to derive this data was a 3-in x 3-in, two-layer board with 2-oz copper traces on top of the board.
- (2) The JEDEC High-K (2s2p) board design used to derive this data was a 3-in x 3-in, multilayer board with 1-oz internal power and ground planes and 2-oz copper traces on top and bottom of the board.

## ELECTRICAL CHARACTERISTICS

Over operating junction temperature range ( $T_J = -55^\circ\text{C}$  to  $125^\circ\text{C}$ ),  $V_{IN} = V_{OUT(NOM)} + 1\text{ V}$ ,  $I_{OUT} = 1\text{ mA}$ , and  $C_{OUT} = 1\text{ }\mu\text{F}$  (unless otherwise noted). Typical values are at  $T_J = 25^\circ\text{C}$ .

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Input voltage <sup>(1)</sup>	$V_{IN}$	$I_O = 10\text{ mA}$	2.5		24	V
		$I_O = 50\text{ mA}$	3		24	
$V_{OUT}$ voltage range			1.2		15	V
$V_{OUT}$ accuracy <sup>(1)</sup>	Over $V_{IN}$ , $I_{OUT}$ , and temperature	$V_{IN} + 1.0\text{ V} \leq V_{IN} \leq 24\text{ V}$ $100\text{ }\mu\text{A} \leq I_{OUT} \leq 50\text{ mA}$	-6.25		+6.25	%
Ground pin current <sup>(2)</sup>	$I_{GND}$	$0 \leq I_{OUT} \leq 50\text{ mA}$ , $T_J = -40^\circ\text{C}$ to $+85^\circ\text{C}$		3.2	4.2	$\mu\text{A}$
		$0\text{ mA} \leq I_{OUT} \leq 50\text{ mA}$		3.2	4.8	
		$0\text{ mA} \leq I_{OUT} \leq 50\text{ mA}$ , $V_{IN} = 24\text{ V}$			5.8	
Load regulation	$\Delta V_{OUT}/\Delta I_{OUT}$	$I_{OUT} = 100\text{ }\mu\text{A}$ to $50\text{ mA}$		22		mV
Output voltage line regulation <sup>(1)</sup>	$\Delta V_{OUT}/\Delta V_{IN}$	$V_{OUT} + 1\text{ V} < V_{IN} \leq 24\text{ V}$		20	75	mV
Output noise voltage	$V_n$	$BW = 200\text{ Hz}$ to $100\text{ kHz}$ , $C_{OUT} = 10\text{ }\mu\text{F}$ , $I_{OUT} = 50\text{ mA}$		575		$\mu\text{V}_{rms}$
Output current limit	$I_{CL}$	$V_{OUT} = 0\text{ V}$ , $V_{IN} \geq 3.5\text{ V}$	125		750	mA
		$V_{OUT} = 0\text{ V}$ , $V_{IN} < 3.5\text{ V}$	90		750	mA
Power-supply ripple rejection	PSRR	$f = 100\text{ kHz}$ , $C_{OUT} = 10\text{ }\mu\text{F}$		60		dB
Dropout voltage $V_{IN} = V_{OUT(NOM)} - 1\text{ V}$	$V_{DO}$	$I_{OUT} = 50\text{ mA}$		415	750	mV

(1) Minimum  $V_{IN} = V_{OUT} + V_{DO}$  or the value shown for *Input voltage* in this table, whichever is greater.

(2) See [Figure 1](#). The TPS71501 employs a leakage null control circuit. This circuit is active only if output current is less than pass FET leakage current. The circuit is typically active when output load is less than  $5\text{ }\mu\text{A}$ ,  $V_{IN}$  is greater than  $18\text{ V}$ , and die temperature is greater than  $100^\circ\text{C}$ .

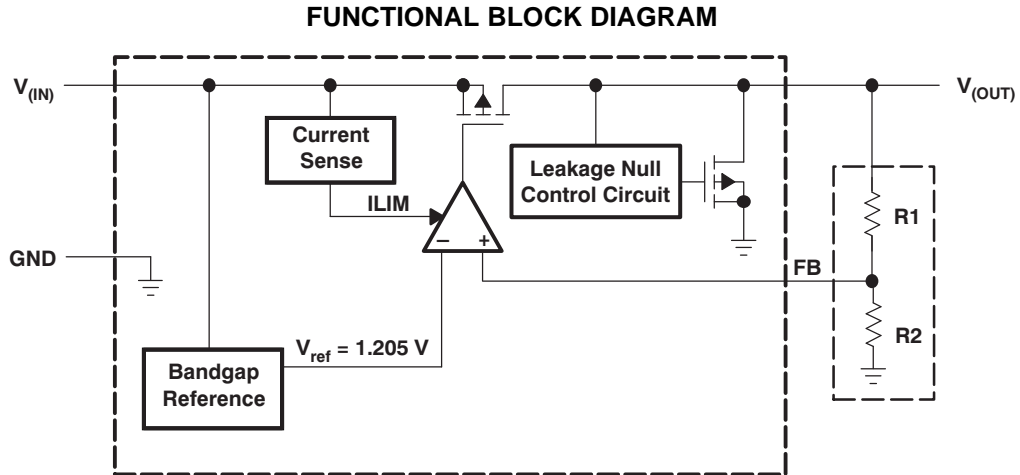


Figure 1. Functional Block Diagram

Table 1. Terminal Functions

TERMINAL		DESCRIPTION
NAME	NO.	
FB	1	Feedback. This terminal is used to set the output voltage.
GND	2	Ground
NC	3	No connection
IN	4	Input supply
OUT	5	Output of the regulator, any output capacitor $\geq 0.47 \mu\text{F}$ can be used for stability.

TYPICAL CHARACTERISTICS

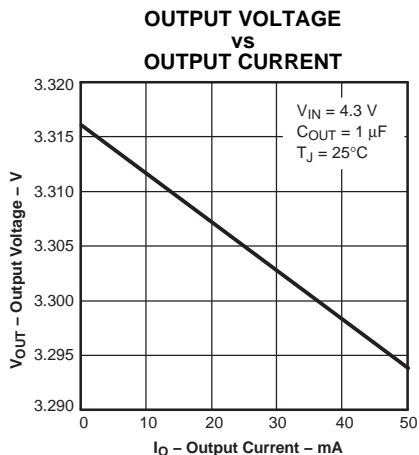


Figure 2.

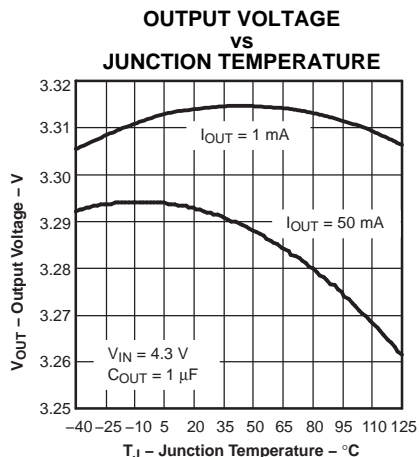


Figure 3.

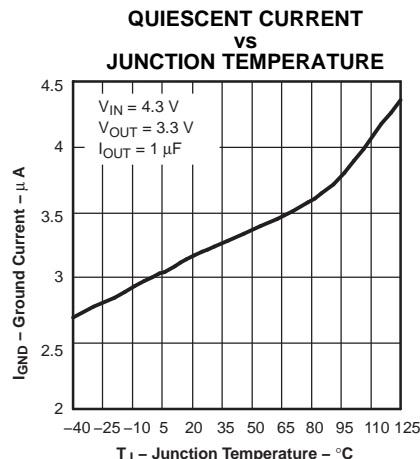


Figure 4.

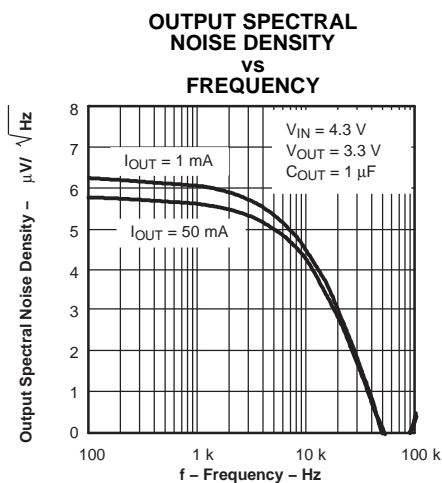


Figure 5.

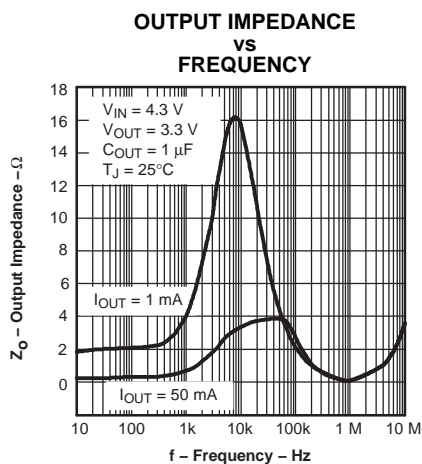


Figure 6.

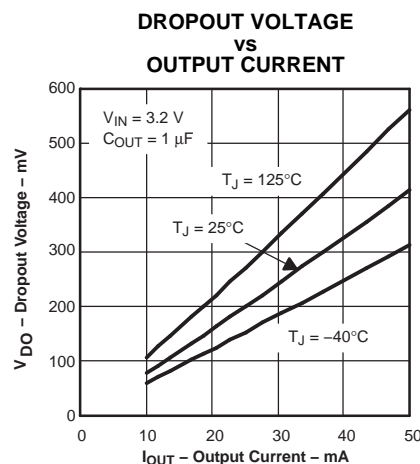


Figure 7.

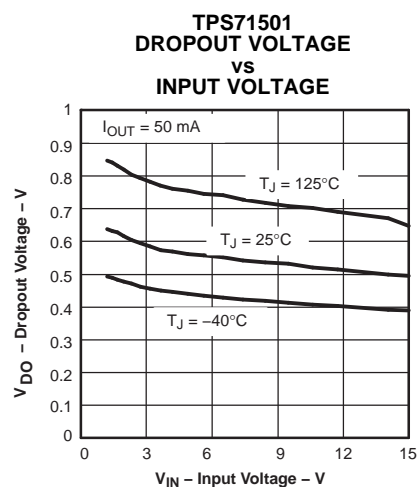


Figure 8.

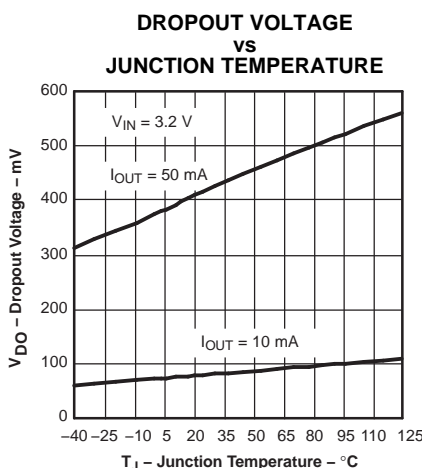


Figure 9.

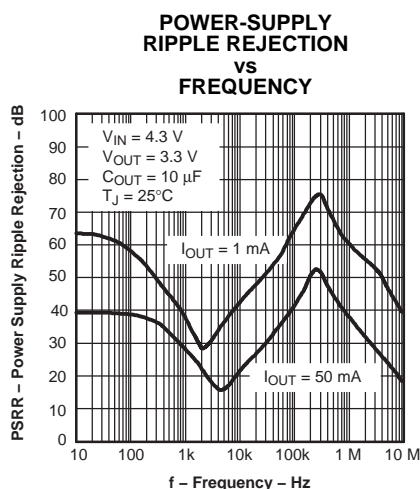


Figure 10.

TYPICAL CHARACTERISTICS (continued)

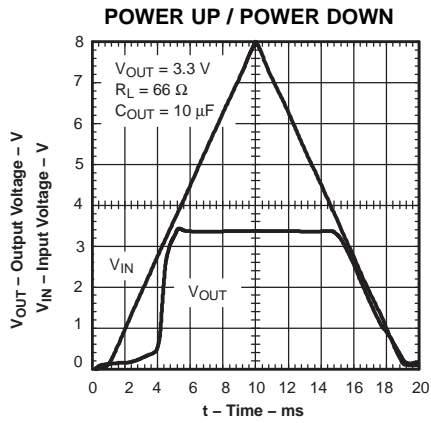


Figure 11.

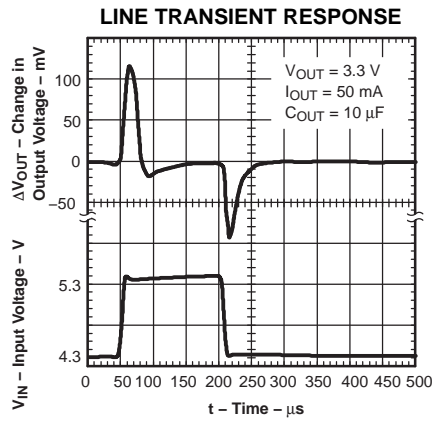


Figure 12.

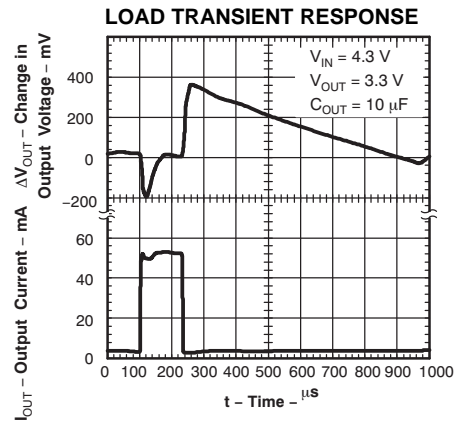


Figure 13.

## APPLICATION INFORMATION

The TPS71501 LDO regulator has been optimized for ultra-low power applications such as the MSP430 microcontroller. Its ultra-low supply current maximizes efficiency at light loads, and its high input voltage range makes it suitable for supplies such as unconditioned solar panels.

### External Capacitor Requirements

Although not required, a 0.047- $\mu$ F or larger input bypass capacitor, connected between IN and GND and located close to the device, is recommended to improve transient response and noise rejection of the power supply as a whole. A higher-value input capacitor may be necessary if large, fast-rise-time load transients are anticipated and the device is located several inches from the power source.

The TPS71501 requires an output capacitor connected between OUT and GND to stabilize the internal control loop. Any capacitor (including ceramic and tantalum)  $\geq 0.47 \mu$ F properly stabilizes this loop. X7R type capacitors are recommended but X5R and others may be used.

### Power Dissipation and Junction Temperature

To ensure reliable operation, worst-case junction temperature should not exceed +125°C. This restriction limits the power dissipation the regulator can handle in any given application. To ensure the junction temperature is within acceptable limits, calculate the maximum allowable dissipation,  $P_{D(max)}$ , and the actual dissipation,  $P_D$ , which must be less than or equal to  $P_{D(max)}$ .

The maximum-power-dissipation limit is determined using the following equation:

$$P_{D(max)} = \frac{T_{Jmax} - T_A}{R_{\theta JA}} \quad (1)$$

where:

- $T_{Jmax}$  is the maximum allowable junction temperature.
- $R_{\theta JA}$  is the thermal resistance junction-to-ambient for the package (see the [Dissipation Ratings](#) table).
- $T_A$  is the ambient temperature.

The regulator dissipation is calculated using:

$$P_D = (V_{IN} - V_{OUT}) \times I_{OUT} \quad (2)$$

For a higher power package version of the TPS715xx, see the [TPS715Axx](#).

### Regulator Protection

The TPS71501 PMOS-pass transistor has a built-in back diode that conducts reverse current when the input voltage drops below the output voltage (e.g., during power-down). Current is conducted from the output to the input and is not internally limited. If extended reverse voltage operation is anticipated, external limiting might be appropriate.

The TPS71501 features internal current limiting. During normal operation, the TPS71501 limits output current to approximately 500 mA. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. Take care not to exceed the power dissipation ratings of the package.

### Programming the TPS71501 Adjustable LDO Regulator

The output voltage of the TPS71501 adjustable regulator is programmed using an external resistor divider as shown in Figure 14. The output voltage operating range is 1.2 V to 15 V, and is calculated using:

$$V_{OUT} = V_{REF} \times \left( 1 + \frac{R1}{R2} \right) \tag{3}$$

where:

- $V_{REF} = 1.205\text{ V typ}$  (the internal reference voltage)

Resistors R1 and R2 should be chosen for approximately 1.5- $\mu\text{A}$  divider current. Lower value resistors can be used for improved noise performance, but the solution consumes more power. Higher resistor values should be avoided as leakage current into/out of FB across R1/R2 creates an offset voltage that artificially increases/decreases the feedback voltage and thus erroneously decreases/increases  $V_{OUT}$ . The recommended design procedure is to choose  $R2 = 1\text{ M}\Omega$  to set the divider current at 1.5  $\mu\text{A}$ , and then calculate R1 using Equation 4:

$$R1 = \left( \frac{V_{OUT}}{V_{REF}} - 1 \right) \times R2 \tag{4}$$

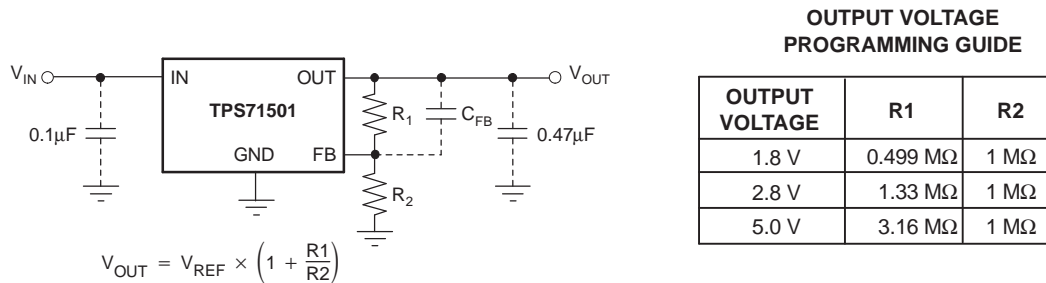


Figure 14. TPS71501 Adjustable LDO Regulator Programming

### Power the MSP430 Microcontroller

Several versions of the TPS715xx are ideal for powering the MSP430 microcontroller. Table 2 shows potential applications of some voltage versions.

Table 2. Typical MSP430 Applications

DEVICE	$V_{OUT}$ (TYP)	APPLICATION
TPS71519	1.9 V	$V_{OUT, MIN} > 1.800\text{ V}$ required by many MSP430s. Allows lowest power consumption operation.
TPS71523	2.3 V	$V_{OUT, MIN} > 2.200\text{ V}$ required by some MSP430s FLASH operation.
TPS71530	3.0 V	$V_{OUT, MIN} > 2.700\text{ V}$ required by some MSP430s FLASH operation.
TPS715345	3.45 V	$V_{OUT, MIN} < 3.600\text{ V}$ required by some MSP430s. Allows highest speed operation.

The TPS715xx family offers many output voltage versions to allow designers to minimize the supply voltage for the processing speed required of the MSP430. This minimizes the supply current consumed by the MSP430.



**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
TPS71501MDCKREP	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CVP	<a href="#">Samples</a>
V62/08619-01XE	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CVP	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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**OTHER QUALIFIED VERSIONS OF TPS71501-EP :**

- Catalog: [TPS71501](#)
- Automotive: [TPS71501-Q1](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS71501MDCKREP	SC70	DCK	5	3000	180.0	8.4	2.25	2.4	1.22	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS71501MDCKREP	SC70	DCK	5	3000	202.0	201.0	28.0

DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Falls within JEDEC MO-203 variation AA.

DCK (R-PDSO-G5)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
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Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
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